

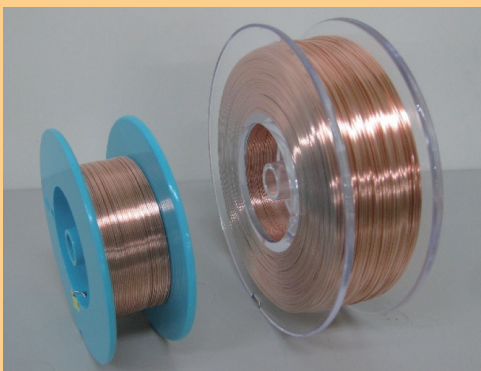
パワーデバイス用 Cuボンディングワイヤ

Cu Heavy Bonding Wire for Power Device

Thick Cu wire (CP-1) $\phi 400, 500\mu\text{m}$

特長 Features

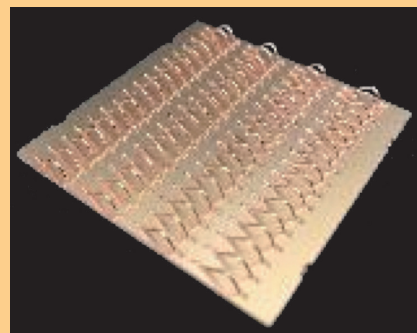
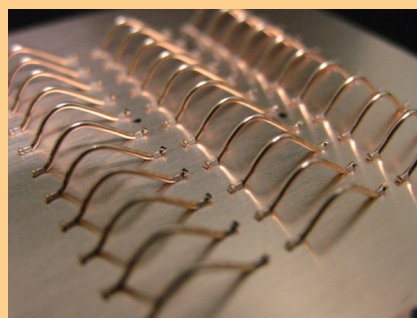
- 低抵抗
Low Resistivity
- 大電流対応
Big current



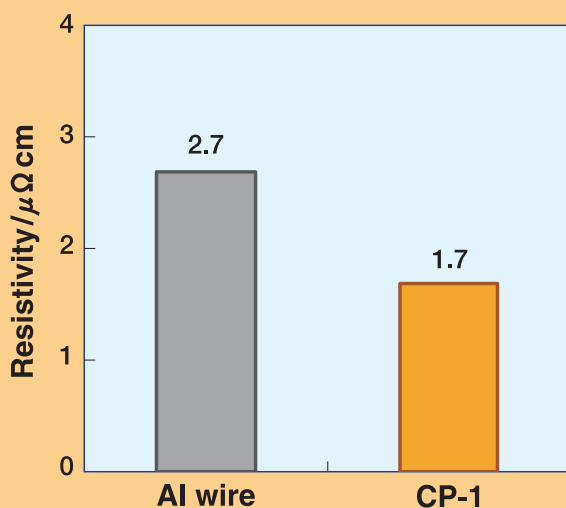
#88 & #120 spool

- Wire size:
 $\phi 400, 500\mu\text{m}$
- Length:
Max 300m

Bonding



Resistivity



Fusing Current

